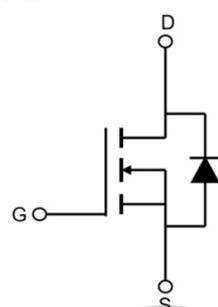
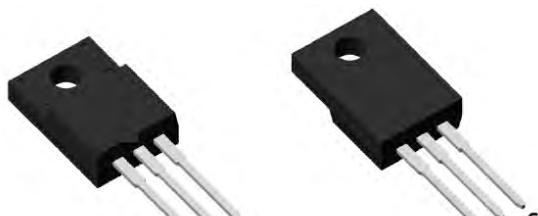


## 500V N-Channel Power MOSFET

**MPR18N50CTF**  
TO-220F



$V_{DS}$	500	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	0.22	$\Omega$
$I_D$	18	A

### Features

- Low gate charge
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

### Applications

- Load Switch for Portable Devices
- DC/DC Converter

**Maximum ratings, at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter		Rating	Unit
$V(BR)DSS$	Drain-Source breakdown voltage		500	V
$V_{GS}$	Gate-Source voltage		$\pm 30$	V
$I_S$	Diode continuous forward current	$T_C = 25^\circ\text{C}$	18	A
$I_D$	Continuous drain current @ $V_{GS}=10\text{V}$	$T_C = 25^\circ\text{C}$	18	A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	72	A
$EAS$	Avalanche energy, single pulsed ②		480	mJ
$P_D$	Power Dissipation	$T_C = 25^\circ\text{C}$	39	W
	Derating Factor above $25^\circ\text{C}$		0.45	$\text{W}/^\circ\text{C}$
$T_{STG,TJ}$	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	1.27	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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### Static Electrical Characteristics @ T<sub>j</sub>=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	500	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
R <sub>D(on)</sub>	Drain-Source On-State Resistance ④	V <sub>GS</sub> =10V, I <sub>D</sub> =9A	--	0.22	0.28	Ω
g <sub>f</sub>	Forward Transconductance	V <sub>DS</sub> =15V, I <sub>D</sub> =9A	--	12	--	S

### Dynamic Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	--	3170	--	pF
C <sub>oss</sub>	Output Capacitance		--	210	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	17	--	pF
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>DS</sub> =400V, I <sub>D</sub> =18A , V <sub>GS</sub> =10V	--	40	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	12	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	11.5	--	nC

## Switching Characteristics

Td(on)	Turn-on Delay Time	V <sub>DD</sub> =250V, I <sub>D</sub> =18A, V <sub>G</sub> =10V, R <sub>G</sub> =25Ω, T <sub>j</sub> =25°C	--	51	--	ns
Tr	Turn-on Rise Time		--	28	--	ns
Td(off)	Turn-Off Delay Time		--	157	--	ns
Tf	Turn-Off Fall Time		--	48	--	ns

## Source- Drain Diode Characteristics@ T<sub>j</sub> = 25°C (unless otherwise stated)

I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current	--	--	72	A
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =18A,V <sub>GS</sub> =0V	--	--	1.4
T <sub>rr</sub>	Reverse Recovery Time	I <sub>s</sub> =18A , V <sub>GS</sub> =0V di/dt=100A/μs	--	450	--
Q <sub>rr</sub>	Reverse Recovery Charge		--	5300	--

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

- ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 10mH. Part not recommended for use above this value
- ③ The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C.
- ④ Pulse width ≤ 380μs; duty cycle≤ 2%.

## Typical Characteristics

Figure 1. Output Characteristics

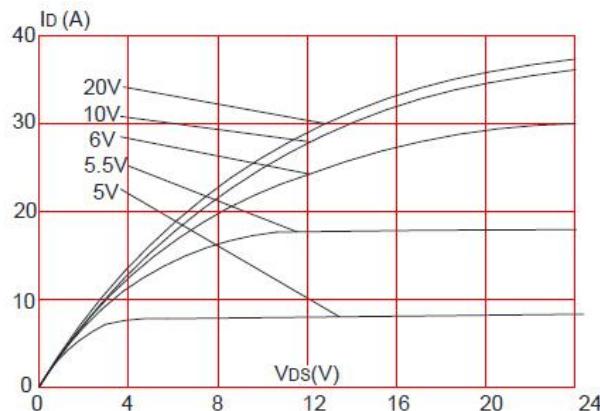


Figure 2. Typical Transfer Characteristics

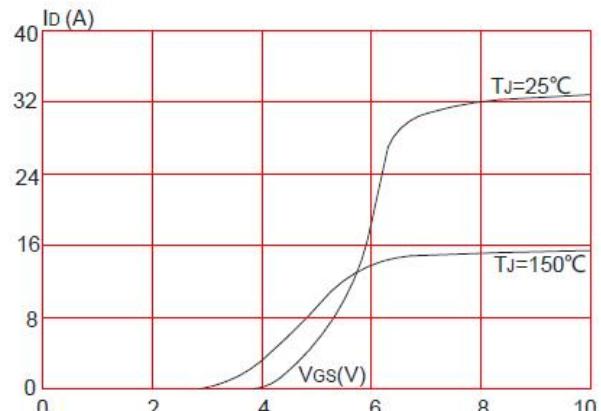


Figure 3. On-resistance vs. Drain Current

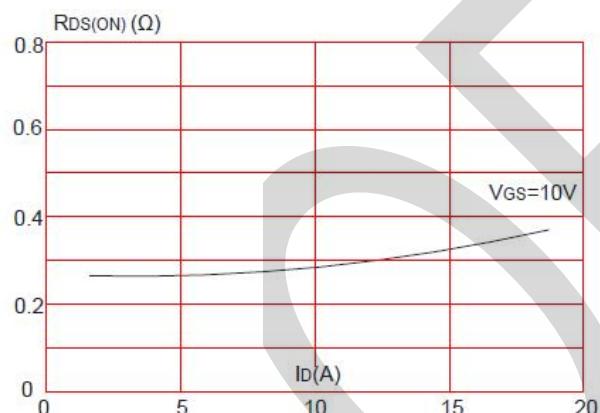


Figure 4. Body Diode Characteristics

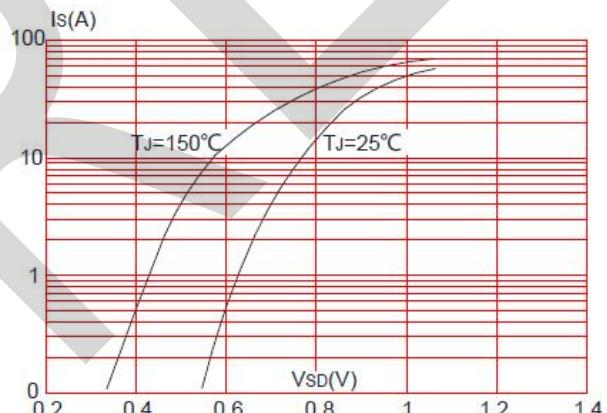


Figure 5. Gate Charge Characteristics

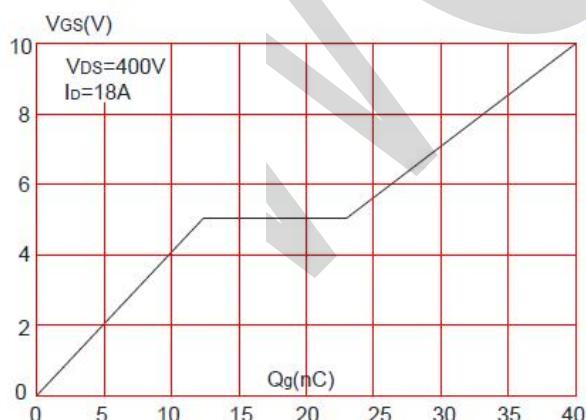
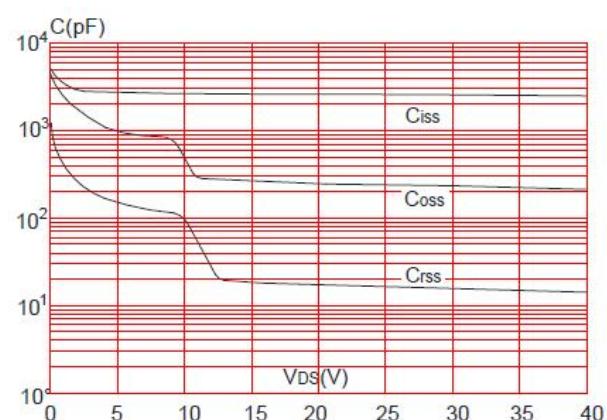


Figure 6. Capacitance Characteristics



## Typical Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

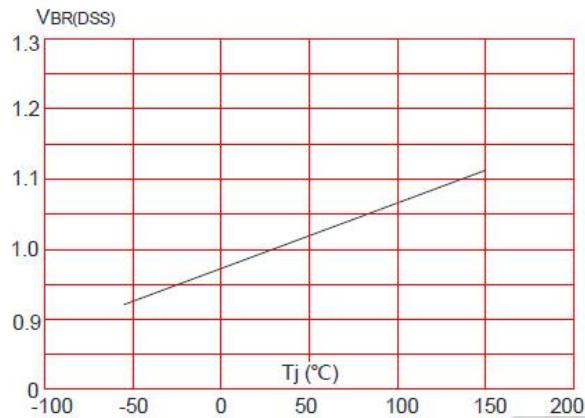


Figure 8: Normalized on Resistance vs. Junction Temperature

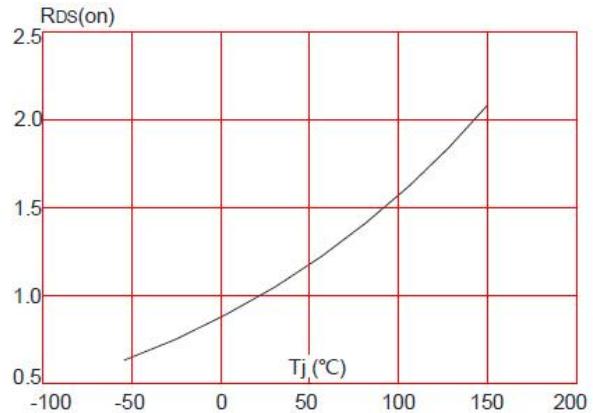


Figure 9: Maximum Safe Operating Area

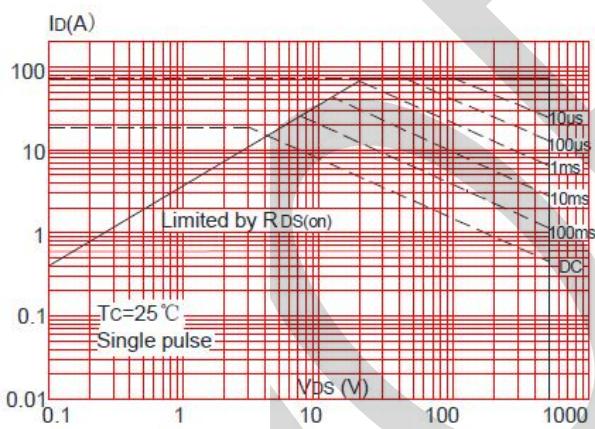


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

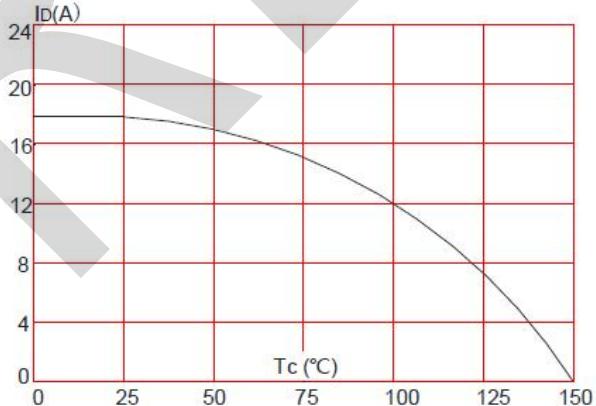
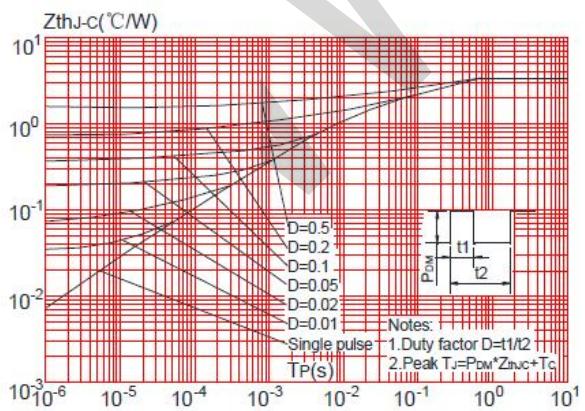
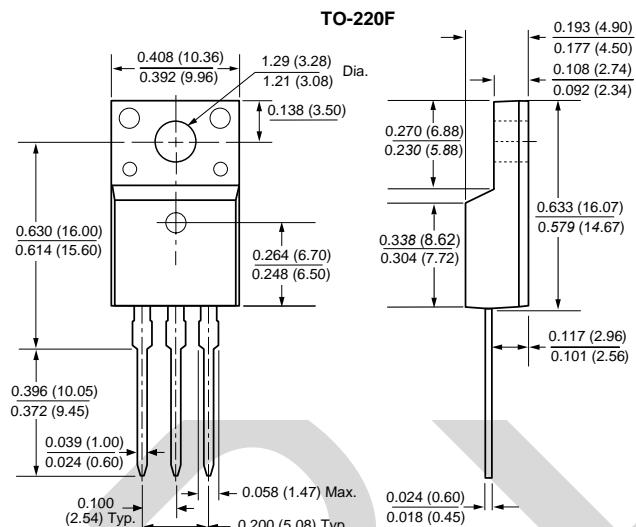


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

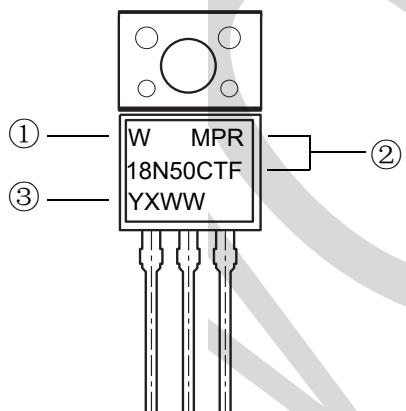


## PACKAGE OUTLINE DIMENSIONS

## **TO-220F Package Information**



## **Marking Information**



- ① W : Company's trademark

- ②Product model : MPR18N50CTF

- ### ③ PDC information:

